


Application No. 10/024,269
Preliminary Amendment dated January 22, 2004

Remarks

Applicants have canceled claims 1-44, and added new claims 45-57. Claims 45-57 remain in the application. Applicants are also enclosing a copy of a translation of a Japanese Laid Open Patent No. 52-118390 originally submitted in an Information Disclosure Statement filed on July 30, 2003.

Applicants respectfully submit that the application is now in condition for allowance and reconsideration of the application is respectfully requested. The Examiner is invited to contact the undersigned in order to resolve any outstanding issues and expedite the allowance of this application.

Respectfully submitted,

By: 
C. Richard Eby, Reg. No. 28,854

WOOD, HERRON & EVANS, L.L.P.
2700 Carew Tower
Cincinnati, Ohio 45202
PH: (513) 241-2324, Ext. 292
FX: (513) 241-6234

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(54) IC WAFER TRANSPORTING CONTAINER

(21) Application No.: Showa 51/33213

(72) Inventor:
T. WATANABE
2-32-17 Hukii, Herima-ku, Tokyo-to

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(71) Applicant:
SEIKEN K.K.
2-7-7, Saru Gaku-cho, Chiyoda-ku,
Tokyo-to

(72) Inventor:
T. ANDO
3-19-19 Ukima, Kita-ku, Tokyo-to

(74) Agent:
H. ASAMURA, Patent Agent and
3 others